PRODUCT CHANGE NOTICE

Alternate Bond Wire Material and Manufacturing Facilities for Assembly of the ISL1533AIRZ* Products

Refer to:
PCN15014

Date : March 06, 2015

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To: Our Valued Intersil Customer

Subject: **Alternate Bond Wire Material and Manufacturing Facilities for Assembly of Intersil's ISL1533AIRZ* Products – *Carsem (CAS) Ipoh, Malaysia***

This notice is to inform you that Intersil will begin using the Carsem (CAS) facility as alternate site for assembly of the ISL1533AIRZ* QFN (Quad Flat No-Lead) packaged products. Products manufactured at the CAS facility will be assembled using copper bond wire as an alternate to the gold bond wire currently used for assembly. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep and equivalent reliability performance. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements.

Products affected:

ISL1533AIRZ
ISL1533AIRZ-T13

The Carsem (CAS) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly of QFN packaged products with both gold and copper bond wire material. Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260 °C per J-STD-020). As such, the listed products will be packed, labeled and shipped as moisture sensitivity level three (MSL 3).

The qualification plan for copper bond wire assembly was designed using JEDEC and other applicable industry standards to confirm form, fit, function, and interchangeability of product. A summary of the qualification results are included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, etc.) will continue to be processed to previously established conditions and systems.

Products affected by this change that are assembled using either gold or copper bond wire material are identifiable via Intersil's internal traceability system and by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at CAS with copper bond wire is "X". The site code for product assembled at CAS with gold bond wire is "F".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product manufactured with the changed materials beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

June Chan

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Intersil Corporation

PCN15014

cc: :
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PCN15014 – Reliability Qualification Results

Stress / Conditions	Duration	ISL1533AIRZ 24 Leads QFN 4mm x 5mm
Moisture Sensitivity Classification		N = 66 Acc = 0 L3 PB FREE
Biased HAST +130°C / 85% RH	96 Hrs	N = 240 Acc = 0
Unbiased HAST +130°C / 85% RH	96 Hrs	N = 240 Acc = 0
High Temperature Storage T_A = +150°C	1000 Hrs	N = 240 Acc = 0
Temp Cycle +150°C / -65°C	500 Cyc	N = 240 Acc = 0

🟩 Qualification Completed and Passed